

ductruong

* * * * * STN Columbus * * * * *

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COST IN U.S. DOLLARS

SINCE FILE

TOTAL

ENTRY

SESSION

FULL ESTIMATED COST

0.21

0.21

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FILE 'USPATOLD' ENTERED AT 11:19:49 ON 15 DEC 2008

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FILE 'USPAT2' ENTERED AT 11:19:49 ON 15 DEC 2008

CA INDEXING COPYRIGHT (C) 2008 AMERICAN CHEMICAL SOCIETY (ACS)

=> s thermoplastic polyimide# and imide oligomer#

L1 32 THERMOPLASTIC POLYIMIDE# AND IMIDE OLIGOMER#

=> s l1 and aromatic tetracarboxylic acid dianhydride#

L2 3 L1 AND AROMATIC TETRACARBOXYLIC ACID DIANHYDRIDE#

=> s l2 and diamine#

L3 1 L2 AND DIAMINE#

=> d

L3 ANSWER 1 OF 1 USPATFULL on STN

AN 2006:289415 USPATFULL

TI Novel thermoplastic polyimide and inide oligomer

IN Inoue, Shinsuke, Hiroshima, JAPAN

Nanba, Satoru, Hiroshima, JAPAN

Inagaki, Hiroyasu, Tokyo, JAPAN

PI US 20060247411 A1 20061102

AI US 2003-528530 A1 20030918 (10)

WO 2003-JP11873 20030918

20050318 PCT 371 date

DT Utility

FS APPLICATION

ductruong

LN.CNT 672
INCL INCLM: 528/170.000
NCL NCLM: 528/170.000
IC IPCI G01N0033-00 [I,A]
IPCR G01N0033-00 [I,C]; G01N0033-00 [I,A]
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

=> s l2 and triple bond#

L4 1 L2 AND TRIPLE BOND#

=> d

L4 ANSWER 1 OF 1 USPATFULL on STN
AN 2006:289415 USPATFULL
TI Novel thermoplastic polyimide and inide oligomer
IN Inoue, Shinsuke, Hiroshima, JAPAN
Nanba, Satoru, Hiroshima, JAPAN
Inagaki, Hiroyasu, Tokyo, JAPAN
PI US 20060247411 A1 20061102
AI US 2003-528530 A1 20030918 (10)
WO 2003-JP11873 20030918
20050318 PCT 371 date
DT Utility
FS APPLICATION
LN.CNT 672
INCL INCLM: 528/170.000
NCL NCLM: 528/170.000
IC IPCI G01N0033-00 [I,A]
IPCR G01N0033-00 [I,C]; G01N0033-00 [I,A]
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

=> s l3 and (PEPA or phenylethynyl phthalic acid anhydride# or
phenylethynylphthalic acid anhydride#)

L5 1 L3 AND (PEPA OR PHENYLETHYNYL PHTHALIC ACID ANHYDRIDE# OR PHENY
LETHYNYLPHthalic ACID ANHYDRIDE#)

=> d l2 1-3

L2 ANSWER 1 OF 3 USPATFULL on STN
AN 2006:289415 USPATFULL
TI Novel thermoplastic polyimide and inide oligomer
IN Inoue, Shinsuke, Hiroshima, JAPAN
Nanba, Satoru, Hiroshima, JAPAN
Inagaki, Hiroyasu, Tokyo, JAPAN
PI US 20060247411 A1 20061102
AI US 2003-528530 A1 20030918 (10)
WO 2003-JP11873 20030918
20050318 PCT 371 date
DT Utility
FS APPLICATION
LN.CNT 672
INCL INCLM: 528/170.000
NCL NCLM: 528/170.000
IC IPCI G01N0033-00 [I,A]
IPCR G01N0033-00 [I,C]; G01N0033-00 [I,A]
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

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L2 ANSWER 2 OF 3 USPATFULL on STN
AN 2002:258598 USPATFULL
TI Underfill material for COF mounting and electronic components
IN Yamaguchi, Hiroaki, Tokyo, JAPAN
Kohda, Masafumi, Ichihara City, JAPAN
PA UBE INDUSTRIES, LTD., UBE CITY, JAPAN (non-U.S. corporation)
PI US 20020142167 A1 20021003
US 6613449 B2 20030902
AI US 2002-58112 A1 20020129 (10)
PRAI JP 2001-20399 20010129
DT Utility
FS APPLICATION
LN.CNT 507
INCL INCLM: 428/413.000
INCLS: 528/403.000
NCL NCLM: 428/620.000; 428/413.000
NCLS: 257/791.000; 257/792.000; 257/793.000; 257/E21.503; 257/E23.119;
528/027.000; 528/117.000; 528/405.000; 528/418.000; 528/403.000
IC [7]
ICM B32B0027-38
ICS C08G0059-00
IPCI B32B0027-38 [ICM,7]; C08G0059-00 [ICS,7]
IPCI-2 H01L0029-12 [ICM,7]; H01L0029-02 [ICM,7,C*]
IPCR H01L0023-16 [I,C*]; H01L0023-18 [I,A]; C08G0059-00 [I,C*];
C08G0059-40 [I,A]; H01L0021-02 [I,C*]; H01L0021-56 [I,A];
H01L0023-28 [I,C*]; H01L0023-29 [I,A]
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L2 ANSWER 3 OF 3 USPAT2 on STN
AN 2002:258598 USPAT2
TI Underfill material for COF mounting and electronic components
IN Yamaguchi, Hiroaki, Tokyo, JAPAN
Kohda, Masafumi, Ichihara, JAPAN
PA UBE Industries, Ltd., Yamaguchi, JAPAN (non-U.S. corporation)
PI US 6613449 B2 20030902
AI US 2002-58112 20020129 (10)
PRAI JP 2001-20399 20010129
DT Utility
FS GRANTED
LN.CNT 492
INCL INCLM: 428/620.000
INCLS: 257/791.000; 257/792.000; 257/793.000; 528/027.000; 528/117.000;
528/405.000; 528/418.000
NCL NCLM: 428/620.000; 428/413.000
NCLS: 257/791.000; 257/792.000; 257/793.000; 257/E21.503; 257/E23.119;
528/027.000; 528/117.000; 528/405.000; 528/418.000; 528/403.000
IC [7]
ICM H01L0029-12
IPCI B32B0027-38 [ICM,7]; C08G0059-00 [ICS,7]
IPCI-2 H01L0029-12 [ICM,7]; H01L0029-02 [ICM,7,C*]
IPCR H01L0023-16 [I,C*]; H01L0023-18 [I,A]; C08G0059-00 [I,C*];
C08G0059-40 [I,A]; H01L0021-02 [I,C*]; H01L0021-56 [I,A];
H01L0023-28 [I,C*]; H01L0023-29 [I,A]
EXF 257/791; 257/792; 257/793; 428/620; 528/27; 528/117; 528/405; 528/418
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

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